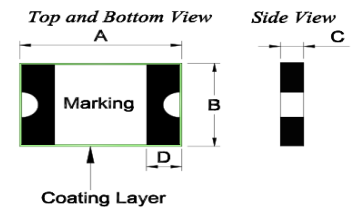


1、Physical Dimensions(size of 2920)

Unit:mm

Part Number	A*		B*		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
LSML600/16TC	6.73	8.22	4.80	5.95	0.40	0.90	0.30	T6A

* Dimension is measured after coating



2、Electrical Characteristics

Part Number	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	T _{trip} (Max time to trip)		Pd _{typ} (W)	R _{min} (Ω)	R1 _{max} (Ω)
					Current(A)	Time(S)			
LSML600/16TC	6.00	12.0	16	50	30.0	7	1.5	0.001	0.008

I_H: Holding Current: maximum current at which the device will not trip in 25°C still air.

I_T: Tripping Current minimum current at which the device will trip in 25°C still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

I_{max}: Maximum fault current device can withstand without damage at rated voltage.

T_{trip}: Maximum time to trip(s) at assigned current.

Pd_{typ}: Rated working power.

R_{min}: Minimum resistance of device prior to trip at 25°C.

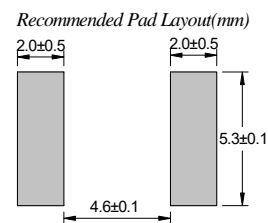
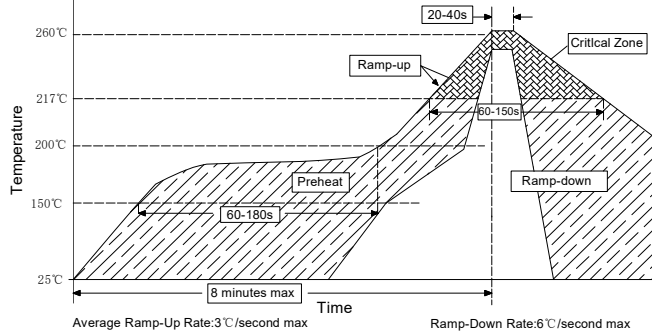
R1_{max}: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

3、Thermal Derating

LSML600/16TC	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	8.80	7.60	6.70	6.00	5.20	4.80	4.30	4.00	3.10
Trip Current(A)	17.6	15.2	13.4	12.0	10.4	9.60	8.60	8.00	6.20

4、Solder Reflow Recommendations



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5、Package Information

Packing quantity:1500 PCS/Reel

Note:Reel packaging per EIA-481-2 standard